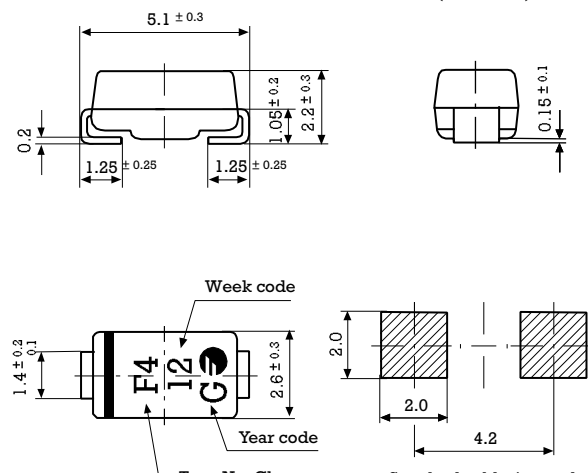


1 Amp. Surface Mounted Schottky Barrier Rectifier

<p>Dimensions in mm.</p>  <p>Week code F4 12 Year code Type No. Class</p> <p>Standard soldering pad</p>	<p>CASE: SMA/DO-214AC (Plastic)</p>	<p>Voltage 20 V to 60 V</p>	<p>Current 1.0 A</p>
<ul style="list-style-type: none"> • Metal Silicon Junction, majority carrier conduction • High current capability, low forward voltage drop • Guardring for overvoltage protection • Low power loss, high efficiency • High surge capability • Plastic material carries U/L recognition 94 V-O • Low profile package • Easy pick and place 			

Maximum Ratings, according to IEC publication No. 134

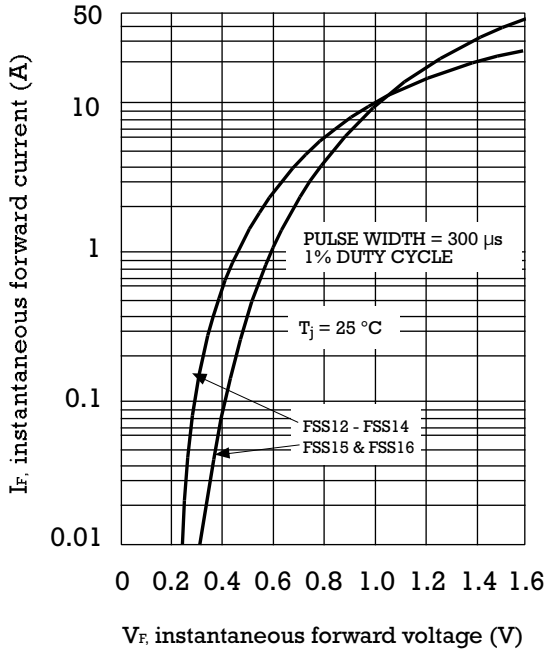
		FSS12	FSS13	FSS14	FSS15	FSS16
Marking Code		A1	A2	A3	A4	A5
V_{RRM}	Peak recurrent reverse voltage (V)	20	30	40	50	60
V_{RMS}	Maximum RMS voltage (V)	14	21	28	35	42
V_{DC}	Maximum DC blocking voltage (V)	20	30	40	50	60
$I_{F(AV)}$	Maximum average Forward current.	1 A				
I_{FSM}	8.3 ms. peak forward surge current (Jedec Method)	40 A				
T_j	Operating temperature range	- 65 to + 125 °C			- 65 to + 150 °C	
T_{stg}	Storage temperature range	- 65 to + 150 °C				

Electrical Characteristics at $T_{amb} = 25\text{ °C}$

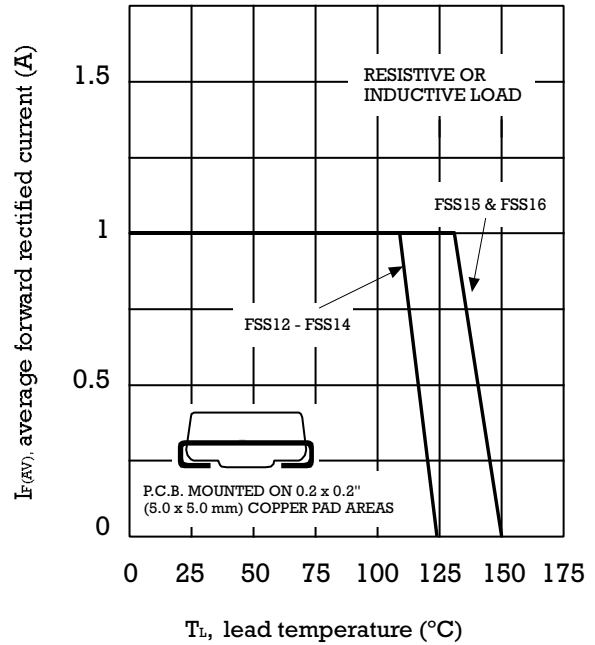
V_F	Max. forward voltage drop at $I_F = 1.0\text{ A}$	0.55 V	0.75 V
I_R	Max. Instantaneous reverse current at V_{RRM} $T_a = 25\text{ °C}$ $T_a = 100\text{ °C}$	0.5 mA	
		10 mA	5 mA
R_{thj-a} R_{thj-l}	Typical Thermal Resistance	88 °C/W 28 °C/W	

NOTE: Thermal Resistance from junction to lead or to ambient PCB mounted with 5x5 mm copper pads areas.

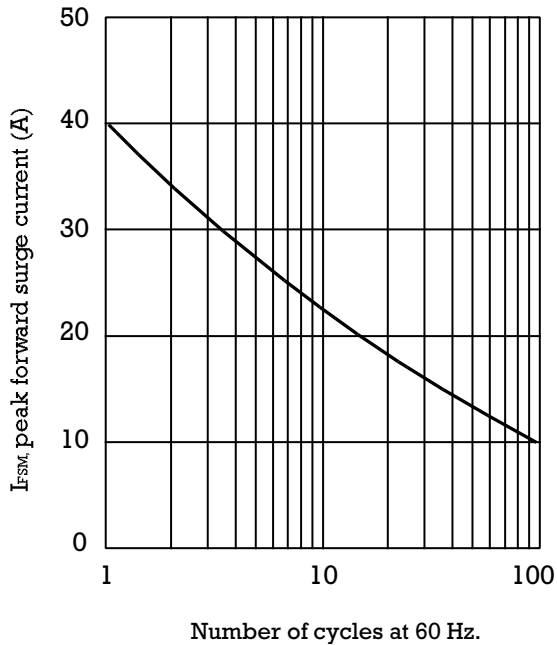
TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



TYPICAL JUNCTION CAPACITANCE

